

Special Issue on Advanced Micro/Nanomaterials for Various Sensor Applications (Selected Papers from ICASI 2024)

Special Issue Information

The 10th IEEE International Conference on Applied System Innovation 2024 (IEEE ICASI 2024, <https://2024.icasf-conf.net/>) will be held in Kyoto, Japan on April 17-21, 2024. The conference will provide a unified communication platform for a wide range of topics of electrical engineering, material science, and related fields.

Various sensors and flexible optoelectronics have been attracting a great deal of attention in recent years due to their potential applications in healthcare monitoring, biomedicine, electronic skin, wearable sensing technology, soft robotics, flat panel displays, safety equipment, smart systems, and future space applications. The aim of this special issue is to publish novel and high-quality research papers (experimental, theoretical, or simulation works) as well as review articles addressing recent advances in cutting-edge flexible electronics and sensors based on micro/nanomaterials. Research and review articles should provide a comprehensive insight into the characterization and understanding of functional micro/nanomaterial properties with the application of scanning techniques. Manuscripts submitted to *Sensors and Materials* must be not published previously or under consideration for publication elsewhere. Potential topics include, but are not limited to:

- Design, synthesis, and characterization of functional micro/nanomaterials for sensing applications and electronic devices
- Chemical and gas sensors based on micro/nano sensing materials
Advanced materials for mechatronics applications
- Molecular dynamics simulations and quantum chemical calculations for micro/nanomaterials related to sensing applications and flexible electronics
- Theories and principles related to micro/nanomaterials, chemical and gas sensing, and flexible electronics
- Sensors and flexible electronics for future food and agricultural applications
- Advanced scanning techniques for characterization of sensors and flexible electronics

Schedule

Manuscript Due: September 30, 2024

First Round of Reviews: October 31, 2024

Second Round of Reviews: November 30, 2024

Acceptance of Final papers: January 31, 2025

Publication (planned): February 28, 2025

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(Attention)

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication. If the quality of the English of your manuscript does not satisfy the journal standards, the authors will bear the proofreading fee, which will be charged with the publication fee. Please refer to the Section 4 of the Instructions to Authors for detailed information on specific price amounts at our website below.

<https://sensors.myu-group.co.jp/permanent/Instructions%20to%20authors2019%20EN.pdf>

If you have any questions, please feel free to contact the editorial staff at the address below.

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